



Customer Information Notification

201404014I

Issue Date: 05-Jun-2014

Effective Date: 06-Jul-2014

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to [view this notification online](#)



QUALITY

Management Summary

- The datasheet is updated, as some corrections were required.

Change Category

| | | | |
|--|---|--|--|
| <input type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input type="checkbox"/> Assembly Materials | <input checked="" type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Update datasheet for LPC407X / LPC408X

Information Notification

The product datasheet LPC407X / LPC408X has been updated to rev. 3.

- Some parameters in the datasheet are updated, specifically an update for static characteristics', Idd max limits, EMC timing and BGA80 and LQFP80 pin out updates, see attachment.
- See datasheet revision history sheet (page 136) for more details.
- BGA80 pin assignment added.

Why do we issue this Information Notification

- The update is made to ensure that the correct information is in the datasheet.
- To notify customers that the product datasheet is updated.

Identification of Affected Products

Product identification does not change.

Impact

No impact.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Not applicable, no changes in the product itself, this is only a datasheet update.

Remarks

- No process / fab change.
- No assembly / final test location change.
- No design change.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Emile Busink
Position QA engineering Logic & Smart Analog / MCU
e-mail address emile.busink@nxp.com

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

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